


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25RU3993-BQFT	FG1X*SF3993A	A	N/A	2019-04-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	142.03	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.9	48	No lead	
Comment	B01X VFQFPN 7X7X1 48L PAD 5.14X5.14 DM00315131			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	FG1X*SF3993A				6000000.0	1000000.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	8.395	mg	supplier	Silicon	Silicon	7440-21-3		7.975	mg	950000	56152
				supplier	Polyimide	Polyimide	58698-66-1		0.420	mg	50000	2955
Leadframe	M-011 Other inorganic materials	61.135	mg	supplier	alloy	Copper	7440-50-8		59.454	mg	972500	418601
				supplier	alloy	Silver	7440-22-4		0.183	mg	3000	1291
				supplier	alloy	Zinc	7440-66-6		0.092	mg	1500	646
				supplier	alloy	Iron	7439-89-6		1.406	mg	23000	9900
Die Attach	M-011 Other inorganic materials	1.207	mg	supplier	glue or soft solder	Epoxy Resin	25928-94-3		0.266	mg	220000	1870
				supplier	glue or soft solder	Silver	7440-22-4		0.929	mg	770000	6544
				supplier	glue or soft solder	Gamma Butyrolactone	96-48-0		0.012	mg	10000	85
Encapsulation	M-011 Other inorganic materials	67.844	mg	supplier	Molding Compound	Phenol Resin	28064-14-4		3.867	mg	57000	27227
				supplier	Molding Compound	Carbon Black	1333-86-4		0.204	mg	3000	1433
				supplier	Molding Compound	Silica Fused	60676-86-0		57.667	mg	850000	406022
				supplier	Molding Compound	Epoxy Resin	25928-94-3		6.106	mg	90000	42991
Finishing	M-011 Other inorganic materials	2.657	mg	supplier	connections coating	Tin	7440-31-5		2.657	mg	1000000	18709
Wire	M-011 Other inorganic materials	0.792	mg	supplier	Bonding wire	Gold	7440-57-5		0.792	mg	1000000	5574